Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
E1	32	(south near epitaxy near corporation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 11:57
L2	0	"10707084"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 11:57
L3	1	"10/707084"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 11:59
L4	3367	high near resistivity near2 layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 11:59
L5	3367	high near resistivity near2 (interlaye or inter-layer or layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 11:59
L6	3368	high near resistivity near2 (interlayer or inter-layer or layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 12:00
L7	30	high near resistivity near2 (interlayer or inter-layer or layer) near2 GaN	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 12:00
L10	193	"Al.sub.xIn.sub.yGa.sub.1-x-yN"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 12:25
L11	209	"Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 12:28

L12	1	((resistive or resistivity) near10 ("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 12:27
L13	2	((resistive or resistivity or interlayer) near10 ("Al.sub.xIn. sub.yGa.sub.1-x-yN" or "Al.sub. aIn.sub.bGa.sub.1-a-bN"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 12:27
L14	2	((resistive or resistivity or interlayer or inter-layer) near10 ("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 12:27
L15	2	((resistive or resistivity or interlayer or inter-layer) near10 (("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub.1-a-bN")))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 12:27
L16	36	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN") and nucleation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 12:28
L17	18	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN") and nucleation and electrode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 13:43
L18	104	(sheu and lai)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 13:50
L19	3481	(257/184.ccls. or 257/190.ccls. or 257/452.ccls. or 257/457.ccls. or 257/461.ccls.)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 13:55
L20	355	I19 and (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 13:51
L21	72	I19 and (leakage near current) and (high near (resistance or resistor or resistivity))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 13:52

		EAST Scare				
L22	22	I19 and (leakage near current) same (high near (resistance or resistor or resistivity))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 13:53
L23	2	l19 and (leakage near current) same (high near (resistance or resistor or resistivity) same (nitride or gan or algan or alingan))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 13:54
L24	5	(257/184.ccls. or 257/190.ccls. or 257/452.ccls. or 257/457.ccls. or 257/459.ccls. or 257/461.ccls.) and ("Al.sub.xIn.sub.yGa.sub. 1-x-yN" or "Al.sub.aIn.sub.bGa. sub.1-a-bN")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 13:55
L25	5	(257/184.ccls. or 257/190.ccls. or 257/452.ccls. or 257/457.ccls. or 257/459.ccls. or 257/461.ccls.) and (("Al.sub.xIn.sub.yGa.sub. 1-x-yN" or "Al.sub.aIn.sub.bGa. sub.1-a-bN"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 13:56
L26		(257/184.ccls. or 257/190.ccls. or 257/452.ccls. or 257/457.ccls. or 257/459.ccls. or 257/461.ccls.) and (("Al.sub.xIn.sub.yGa.sub. 1-x-yN" or "Al.sub.aIn.sub.bGa. sub.1-a-bN")) and (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 13:56
L27	30	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN")) and (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 13:57
L28	3	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN")) same (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:16
L29	340	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or AlInGaN or GaN)) same (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:17
L30	69	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or AlInGaN or GaN)) near10 layer near10 (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:20

L31	89	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or AlInGaN or GaN or (indirum near2 aluminum near2 gallium near2 nitride))) near10 layer with (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:20
L32	205	(("Al sub:xIn.sub:yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or AlInGaN or GaN or (indirum near2 aluminum near2 gallium near2 nitride))) near10 layer same (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:22
L33	1066	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or AlInGaN or GaN or (indirum near2 aluminum near2 gallium near2 nitride) or ((resistor or resistive or resistivity or resistance) near2 layer))) near10 layer same (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2007/04/23 14:21
L34	1238	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or AlInGaN or GaN or (ressitance or resistive or resistivity or resistor) or (indirum near2 aluminum near2 gallium near2 nitride))) near10 layer same (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:22
L35	1238	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or AlInGaN or GaN or (ressitance or resistive or resistivity or resistor) or (indium near2 aluminum near2 gallium near2 nitride))) near10 layer same (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:23
136	444	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or AlInGaN or GaN or (ressitance or resistive or resistivity or resistor) or (indium near2 aluminum near2 gallium near2 nitride))) near10 layer near10 (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:22
L37	862412	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or AlInGaN or GaN or (ressitance or resistive or resistivity or resistor) or (indium near2 aluminum near2 gallium near2 nitride)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:24

L38	29769	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or AlInGaN or GaN or (ressitance or resistive or resistivity or resistor) or (indium near2 aluminum near2 gallium near2 nitride))) and (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:24
L39	47118	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or AlInGaN or GaN or (resistance or resistive or resistivity or resistor) or (indium near2 aluminum near2 gallium near2 nitride))) and (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:24
L40	20478	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or AlInGaN or GaN or (resistance or resistive or resistivity or resistor) or (indium near2 aluminum near2 gallium near2 nitride))) same (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2007/04/23 14:24
L41	352	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or AlInGaN or GaN or (resistance or resistive or resistivity or resistor) or (indium near2 aluminum near2 gallium near2 nitride))) same (leakage near current) and nucleation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:26
L42	1814	(electrode same (semiconductor near layer) same (active near layer) and ohmic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:27
L43	996	(electrode same (semiconductor near layer) same (active near layer) same ohmic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:27
L44	74	(electrode same (semiconductor near layer) same (active near layer) same ohmic same ("Al.sub. aIn.sub.bGa.sub.1-a-bN" or AlInGaN or GaN or (ressitance or resistive or resistivity or resistor) or (indium near2 aluminum near2 gallium near2 nitride)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:29

L45	2	(electrode same (semiconductor	US-PGPUB;	OR	ON	2007/04/23 14:29
LTS	2	near layer) same (active near layer) same ohmic same ("Al.sub. aIn.sub.bGa.sub.1-a-bN" or AlInGaN or GaN or (ressitance or resistive or resistivity or resistor) or (indium near2 aluminum near2 gallium near2 nitride))) and (leakage near current)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OK .	ON	2007/04/23 14.29
L46	56	(electrode same (semiconductor near layer) same (active near layer) same ("Al.sub.aIn.sub.bGa.sub.1-a-bN" or AlInGaN or GaN or (ressitance or resistive or resistivity or resistor) or (indium near2 aluminum near2 gallium near2 nitride))) and (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:33
L47	164	("Al.sub.aIn.sub.bGa.sub.1-a-bN" or AlInGaN or (indium near2 aluminum near2 gallium near2 nitride)) and (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:36
L48	0	"Al.sub.xIn.sub.yGa.sub.1-x-yN" near10 leakage	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:35
L49	0	"Al.sub.xIn.sub.yGa.sub.1-x-yN" with leakage	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:35
L50	193	"Al:sub.xIn.sub.yGa.sub:1-x-yN"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:36
L51	3	"Al.sub.xIn.sub.yGa.sub.1-x-yN" same (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:38
L52	3	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN") same (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:59

		LAST Searc		,		
L53	30	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN") and (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:39
L54	6	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN") and (leakage near current) and nucleation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:39
L55	0	I52 and (strangulation same (dope or doped or doping))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:59
L56	357743	((highly or high) near2 (resistivity or resistance or resistor or resistive))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 15:04
L57	1867	((highly or high) near2 (resistivity or resistance or resistor or resistive)) with (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 15:04
L58	0	((highly or high) near2 (resistivity or resistance or resistor or resistive)) with (leakage near current) with "Al.sub.xIn.sub.yGa. sub.1-x-yN"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 15:05
L59	0	((highly or high) near2 (resistivity or resistance or resistor or resistive)) with (leakage near current) same "Al.sub.xIn.sub. yGa.sub.1-x-yN"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 15:05
L60	0	((highly or high) near2 (resistivity or resistance or resistor or resistive)) same (leakage near current) same "Al.sub.xIn.sub. yGa.sub.1-x-yN"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 15:05
L61	0	(((highly or high) near2 (resistivity or resistance or resistor or resistive)) or high-resistivity) same (leakage near current) same "Al. sub.xIn.sub.yGa.sub.1-x-yN"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 15:05
L62	5	(((highly or high) near2 (resistivity or resistance or resistor or resistive)) or high-resistivity) same "Al.sub.xIn.sub.yGa.sub.1-x-yN"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 15:06

L63	209	"Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 15:07
L64	30	("Al:sub:xIn:sub:yGa:sub:1-x-yN" or "Al:sub:aIn:sub:bGa:sub: 1-a-bN") and (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 15:59
L65	1	I64 and ((current near2 strangulation) near10 (implant or implanting or implanted or implantation))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 15:52
L66	40	(US-20040080010-\$ or US-20030062525-\$ or US-20030015708-\$ or US-20030146444-\$ or US-20050012113-\$ or US-20020074553-\$ or US-20020074553-\$ or US-20060199289-\$ or US-20060226417-\$ or US-20030122147-\$ or US-20030127658-\$ or US-20030127658-\$ or US-20030214807-\$ or US-20030214807-\$ or US-20050082543-\$ or US-20050082543-\$ or US-20050071276-\$ or US-20030071276-\$ or US-20030071276-\$ or US-20030047744-\$ or US-20030047744-\$ or US-20030047744-\$ or US-5686272-\$ or US-5677538-\$ or US-5598014-\$ or US-6455340-\$ or US-59905-\$ or US-5717235-\$ or US-5932905-\$ or US-5717235-\$ or US-5707887-\$ or US-5707881-\$ or US-6208074-\$ or US-5673220-\$ or US-7151281-\$).did. or (US-20030230235-\$ or US-20050032345-\$ or US-20050032345-\$ or US-20050032345-\$ or US-20050032313-\$ or US-20050012113-\$ or US-200500121	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2007/04/23 15:58

L67	71	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN") same (active near layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 15:59
L68	73	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or "Al.sub.eIn.sub.fGa. sub.1-e-fN") same (active near layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:00
L69	35	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or "Al.sub.eIn.sub.fGa. sub.1-e-fN") near10 (active near layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:00
L70	69	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or "Al.sub.eIn.sub.fGa. sub.1-e-fN") near10 ((semiconductor or active) near layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:06
L71	1	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or "Al.sub.eIn.sub.fGa. sub.1-e-fN") near10 ((semiconductor or active) near layer) and (electrode near10 (finger or interlaced))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:04
L72	1	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or "Al.sub.eIn.sub.fGa. sub.1-e-fN") near10 ((semiconductor or active) near layer) and ((finger-shaped or finger or interlaced))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:04
L73	26	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or "Al.sub.eIn.sub.fGa. sub.1-e-fN") near10 ((semiconductor or active) near layer).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:04
L74	8 4-52-55 PM	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or "Al.sub.eIn.sub.fGa. sub.1-e-fN") near10 ((semiconductor or active) near layer) and ("Al.sub.xIn.sub.yGa. sub.1-x-yN" or "Al.sub.aIn.sub. bGa.sub.1-a-bN" or "Al.sub.eIn. sub.fGa.sub.1-e-fN") near10 ((nucleation or buffer) near layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:08

L75	4	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or "Al.sub.eIn.sub.fGa. sub.1-e-fN") near10 ((semiconductor or active) near layer) and ("Al.sub.xIn.sub.yGa. sub.1-x-yN" or "Al.sub.aIn.sub. bGa.sub.1-a-bN" or "Al.sub.eIn. sub.fGa.sub.1-e-fN") near10 ((nucleation or buffer) near layer) and ("Al.sub.xIn.sub.yGa.sub. 1-x-yN" or "Al.sub.aIn.sub.bGa. sub.1-a-bN" or "Al.sub.eIn.sub.fGa.sub.1-a-bN" or "Al.sub.eIn.sub.fGa.sub.1-a-bN" or "Al.sub.eIn.sub.fGa.sub.1-a-fN") near10 ((clad or contact) near layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:08
L76	4	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or "Al.sub.eIn.sub.fGa. sub.1-e-fN") near10 ((semiconductor or active) near layer) and ("Al.sub.xIn.sub.yGa. sub.1-x-yN" or "Al.sub.aIn.sub. bGa.sub.1-a-bN" or "Al.sub.eIn. sub.fGa.sub.1-e-fN") near10 ((nucleation or buffer) near layer) and ("Al.sub.xIn.sub.yGa.sub. 1-x-yN" or "Al.sub.aIn.sub.bGa. sub.1-a-bN" or "Al.sub.eIn.sub. fGa.sub.1-e-fN") near10 ((cladding or clad or contact) near layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:09
L77	5	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or "Al.sub.eIn.sub.fGa. sub.1-e-fN" or "Al.sub.cIn.sub. dGa.sub.1-c-dN" ) near10 ((semiconductor or active) near layer) and ("Al.sub.xIn.sub.yGa. sub.1-x-yN" or "Al.sub.aIn.sub. bGa.sub.1-a-bN" or "Al.sub.eIn. sub.fGa.sub.1-e-fN" or "Al.sub.cIn. sub.dGa.sub.1-c-dN") near10 ((nucleation or buffer) near layer) and ("Al.sub.xIn.sub.yGa.sub. 1-x-yN" or "Al.sub.aIn.sub.bGa. sub.1-a-bN" or "Al.sub.eIn.sub. fGa.sub.1-e-fN" or "Al.sub.cIn.sub. dGa.sub.1-c-dN") near10 ((cladding or clad or contact) near layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:10

	1	T	1	1	1	T
L78	41	(US-20040080010-\$ or	US-PGPUB;	OR	ON	2007/04/23 16:25
		US-20030062525-\$ or	USPAT;		ļ	
		US-20030015708-\$ or	JPO;			
		US-20030146444-\$ or	DERWENT			
		US-20050012113-\$ or			ľ	
		US-20020074553-\$ or				
		US-20030218183-\$ or				
		US-20060199289-\$ or				
		US-20060226417-\$ or				
	!	US-20030122147-\$ or				
		US-20020096687-\$ or				
		US-20030127658-\$ or				
		US-20030214807-\$ or	İ			
<b>i</b> .		US-20050082543-\$ or				
	į	US-20050167680-\$ or				
		US-20050274964-\$ or			ļ	
		US-20030071276-\$ or	1	}		
		US-20030047744-\$ or	Ī			
		US-20050167697-\$ or		İ		
		US-20040124435-\$).did. or				
		(US-6586272-\$ or US-5677538-\$				
		or US-5598014-\$ or US-6455340-\$				
		or US-5847397-\$ or US-6495852-\$				
		or US-6429467-\$ or US-5977565-\$			1	
		or US-5932905-\$ or US-5717235-\$				
		or US-5707887-\$ or US-5507881-\$				
		or US-6208074-\$ or US-5673220-\$				
	}	or US-7151281-\$).did. or				
		(JP-06216404-\$).did. or				
		(US-20030230235-\$ or		İ		
		US-20050032345-\$ or				
		JP-06216404-\$ or				
		US-20050012113-\$ or				
		EP-296371-\$).did.				
170	<b>1</b>		HC DCDHD:	OB	ON	2007/04/22 16:20
L79	4		US-PGPUB;	OR	ON	2007/04/23 16:28
S.S. Sygner		or finger-shaped or interlaced))	USPAT;			
			EPO; JPO;			
			DERWENT;		,	
			IBM_TDB			
L80	4	I78 and (electrode near10 (finger	US-PGPUB;	OR	ON	2007/04/23 16:28
		or finger-shaped or interlaced) or	USPAT;		ļ !	
		interdigitated)	EPO; JPO;			
		-	DERWENT;			
			IBM_TDB			
L81	25234	(electrode near10 (finger or	US-PGPUB;	OR	ON	2007/04/22 16:20
LUI	۲۵۲۵	finger-shaped or interlaced) or		UK	UN	2007/04/23 16:28
		interdigitated)	USPAT;			
		interdigitated)	EPO; JPO;			
			DERWENT; IBM_TDB			
			מטו_ויוסנ			

L82	192	((nucleation or buffer) near layer) and ((active or semicondcutor) near layer) and (electrode near10 (finger or finger-shaped or interlaced) or interdigitated)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:29
L83	134	((nucleation or buffer) near layer) and ((active or semicondcutor) near layer) and ((contact or clad or cladding) near layer) and (electrode near10 (finger or finger-shaped or interlaced) or interdigitated)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:30
L84	77	((nucleation or buffer) near layer) and ((active or semicondcutor) near layer) and ((contact or clad or cladding) near layer) and (electrode near10 (finger or finger-shaped or interlaced) or interdigitated) and nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:30
L85	78	((nucleation or buffer) near layer) and ((active or semicondcutor) near layer) and ((contact or clad or cladding) near layer) and (electrode near10 (finger or finger-shaped or interlaced) or interdigitated) and (nitride or GaN)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:30